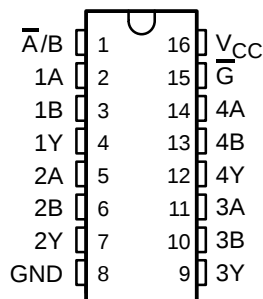


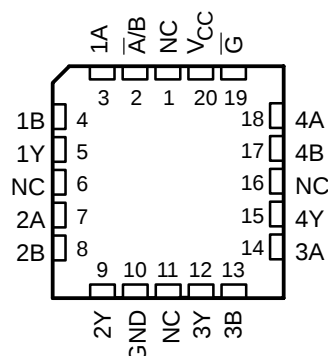
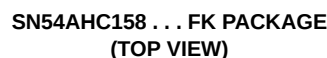
SCLS346G – MAY 1996 – REVISED JULY 2003

- SN54AHC158 . . . J OR W PACKAGE
SN74AHC158 . . . D, DB, DGV, N, NS, OR PW PACKAGE
(TOP VIEW)



These quadruple 2-line to 1-line data selectors/multiplexers are designed for 2-V to 5.5-V V_{CC} operation.

The 'AHC158 devices feature a common strobe ($\overline{G}$) input. When the strobe is high, all outputs are high. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. These devices provide inverted data.



ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AHC158N	SN74AHC158N
	SOIC – D	Tube	SN74AHC158D	AHC158
		Tape and reel	SN74AHC158DR	
	SOP – NS	Tape and reel	SN74AHC158NSR	AHC158
	SSOP – DB	Tape and reel	SN74AHC158DBR	HA158
	TSSOP – PW	Tube	SN74AHC158PW	HA158
		Tape and reel	SN74AHC158PWR	
TVSOP – DGV	Tape and reel	SN74AHC158DGVR	HA158	
–55°C to 125°C	CDIP – J	Tube	SNJ54AHC158J	SNJ54AHC158J
	CFP – W	Tube	SNJ54AHC158W	SNJ54AHC158W
	LCCC – FK	Tube	SNJ54AHC158FK	SNJ54AHC158FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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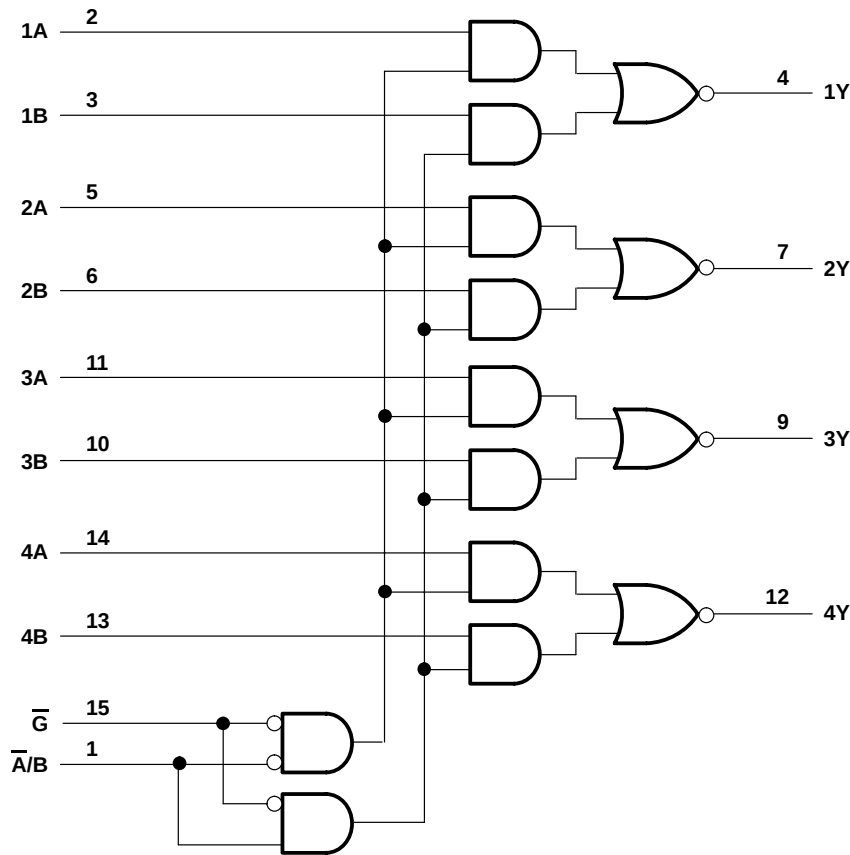
SN54AHC158, SN74AHC158
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS346G – MAY 1996 – REVISED JULY 2003

FUNCTION TABLE
(each data selector/multiplexer)

INPUTS				OUTPUT Y
$\overline{G}$	$\overline{A/B}$	A	B	
H	X	X	X	H
L	L	L	X	H
L	L	H	X	L
L	H	X	L	H
L	H	X	H	L

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, and W packages.

SN54AHC158, SN74AHC158

QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS346G – MAY 1996 – REVISED JULY 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	73°C/W
DB package	82°C/W
DGV package	120°C/W
N package	67°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54AHC158		SN74AHC158		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	5.5	2	5.5	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V	1.5		1.5		V
		$V_{CC} = 3$ V	2.1		2.1		
		$V_{CC} = 5.5$ V	3.85		3.85		
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V		0.5		0.5	V
		$V_{CC} = 3$ V		0.9		0.9	
		$V_{CC} = 5.5$ V		1.65		1.65	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 2$ V		–50		–50	µA
		$V_{CC} = 3.3$ V ± 0.3 V		–4		–4	mA
		$V_{CC} = 5$ V ± 0.5 V		–8		–8	
I_{OL}	Low-level output current	$V_{CC} = 2$ V		50		50	µA
		$V_{CC} = 3.3$ V ± 0.3 V		4		4	mA
		$V_{CC} = 5$ V ± 0.5 V		8		8	
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3.3$ V ± 0.3 V		100		100	ns/V
		$V_{CC} = 5$ V ± 0.5 V		20		20	
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54AHC158, SN74AHC158

QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS346G – MAY 1996 – REVISED JULY 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHC158		SN74AHC158		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = –50 µA	2 V	1.9	2		1.9		1.9		V
		3 V	2.9	3		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		
	I _{OH} = –4 mA	3 V	2.58			2.48		2.48		
	I _{OH} = –8 mA	4.5 V	3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 µA	2 V			0.1		0.1		0.1	V
		3 V			0.1		0.1		0.1	
		4.5 V			0.1		0.1		0.1	
	I _{OL} = 4 mA	3 V			0.36		0.5		0.44	
	I _{OL} = 8 mA	4.5 V			0.36		0.5		0.44	
I _I	A or B inputs	V _I = 5.5 V or GND	0 V to 5.5 V		±0.1		±1*		±1	µA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		40		40	µA
C _i	V _I = V _{CC} or GND	5 V		2	10				10	pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHC158		SN74AHC158		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Y	C _L = 15 pF	6.2**	9.7**		1**	11.5**	1	11.5	ns
t _{PHL}				6.2**	9.7**		1**	11.5**	1	11.5	
t _{PLH}	$\bar{A}/B$	Y	C _L = 15 pF	8.4**	13.2**		1**	15.5**	1	15.5	ns
t _{PHL}				8.4**	13.2**		1**	15.5**	1	15.5	
t _{PLH}	$\bar{G}$	Y	C _L = 15 pF	8.7**	13.6**		1**	16**	1	16	ns
t _{PHL}				8.7**	13.6**		1**	16**	1	16	
t _{PLH}	A or B	Y	C _L = 50 pF	8.7	13.2		1	15	1	15	ns
t _{PHL}				8.7	13.2		1	15	1	15	
t _{PLH}	$\bar{A}/B$	Y	C _L = 50 pF	10.9	16.7		1	19	1	19	ns
t _{PHL}				10.9	16.7		1	19	1	19	
t _{PLH}	$\bar{G}$	Y	C _L = 50 pF	11.2	17.1		1	19.5	1	19.5	ns
t _{PHL}				11.2	17.1		1	19.5	1	19.5	

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SN54AHC158, SN74AHC158

QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS346G – MAY 1996 – REVISED JULY 2003

**switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHC158		SN74AHC158		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Y	C _L = 15 pF	4.1*	6.4*	1*	7.5*	1	7.5	ns	
t _{PHL}				4.1*	6.4*	1*	7.5*	1	7.5		
t _{PLH}	$\bar{A}/B$	Y	C _L = 15 pF	5.3*	8.1*	1*	9.5*	1	9.5	ns	
t _{PHL}				5.3*	8.1*	1*	9.5*	1	9.5		
t _{PLH}	$\bar{G}$	Y	C _L = 15 pF	5.6*	8.6*	1*	10*	1	10	ns	
t _{PHL}				5.6*	8.6*	1*	10*	1	10		
t _{PLH}	A or B	Y	C _L = 50 pF	5.6	8.4	1	9.5	1	9.5	ns	
t _{PHL}				5.6	8.4	1	9.5	1	9.5		
t _{PLH}	$\bar{A}/B$	Y	C _L = 50 pF	6.8	10.1	1	11.5	1	11.5	ns	
t _{PLH}				6.8	10.1	1	11.5	1	11.5		
t _{PLH}	$\bar{G}$	Y	C _L = 50 pF	7.1	10.6	1	12	1	12	ns	
t _{PHL}				7.1	10.6	1	12	1	12		

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 4)

PARAMETER		SN74AHC158			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}			0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}			−0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}			4.8	V
$V_{IH(D)}$	High-level dynamic input voltage		3.5		V
$V_{IL(D)}$	Low-level dynamic input voltage		1.5		V

NOTE 4: Characteristics are for surface-mount packages only.

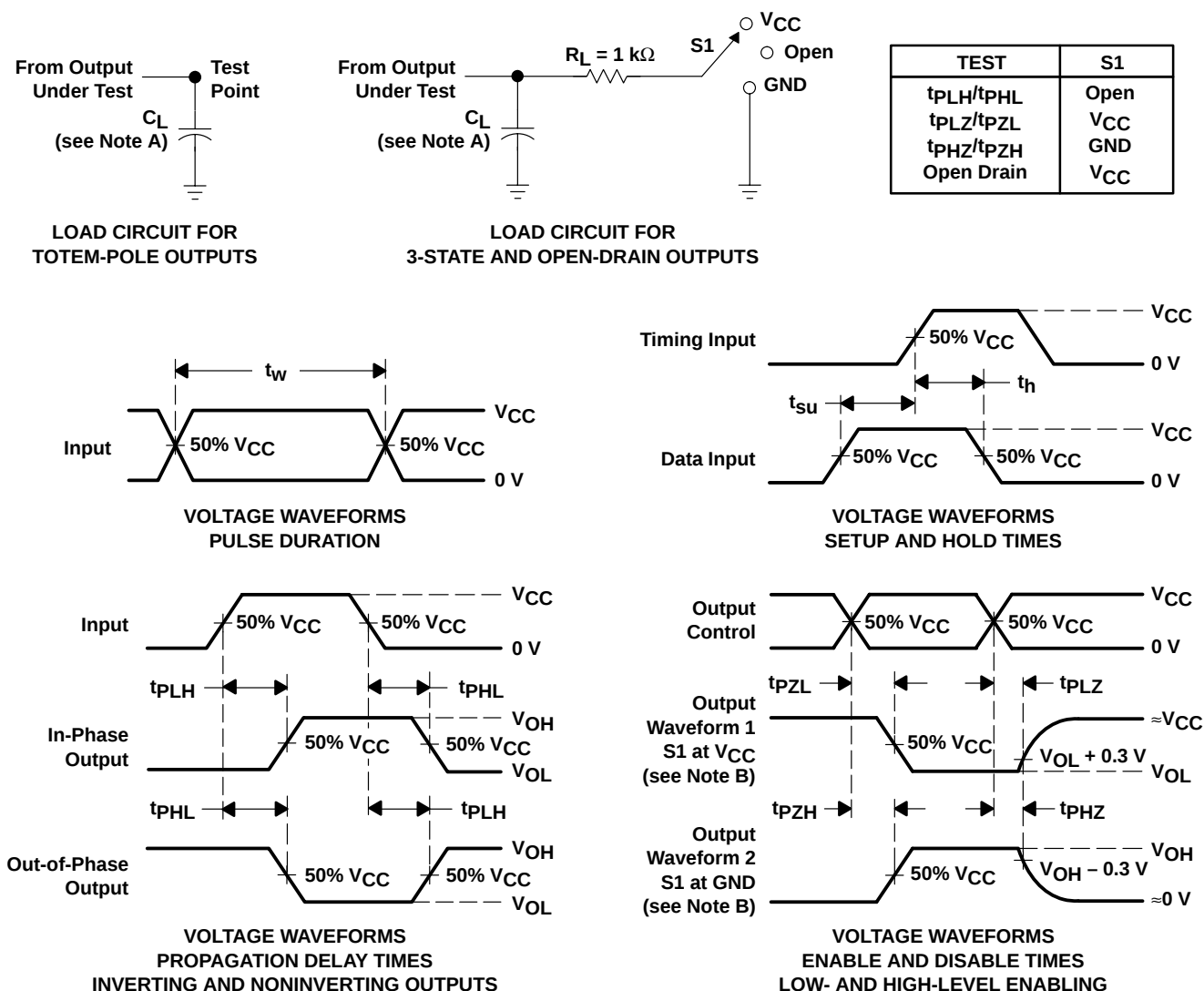
operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load, $f = 1\text{ MHz}$	11	pF

SN54AHC158, SN74AHC158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS346G – MAY 1996 – REVISED JULY 2003

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 D. The outputs are measured one at a time with one input transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74AHC158D	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	AHC158
SN74AHC158DBR	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA158
SN74AHC158DBR.A	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA158
SN74AHC158DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC158
SN74AHC158DR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC158
SN74AHC158N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74AHC158N
SN74AHC158N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74AHC158N
SN74AHC158PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA158
SN74AHC158PWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA158

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC158DBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74AHC158DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AHC158PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC158DBR	SSOP	DB	16	2000	353.0	353.0	32.0
SN74AHC158DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74AHC158PWR	TSSOP	PW	16	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74AHC158N	N	PDIP	16	25	506	13.97	11230	4.32
SN74AHC158N	N	PDIP	16	25	506	13.97	11230	4.32
SN74AHC158N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74AHC158N.A	N	PDIP	16	25	506	13.97	11230	4.32

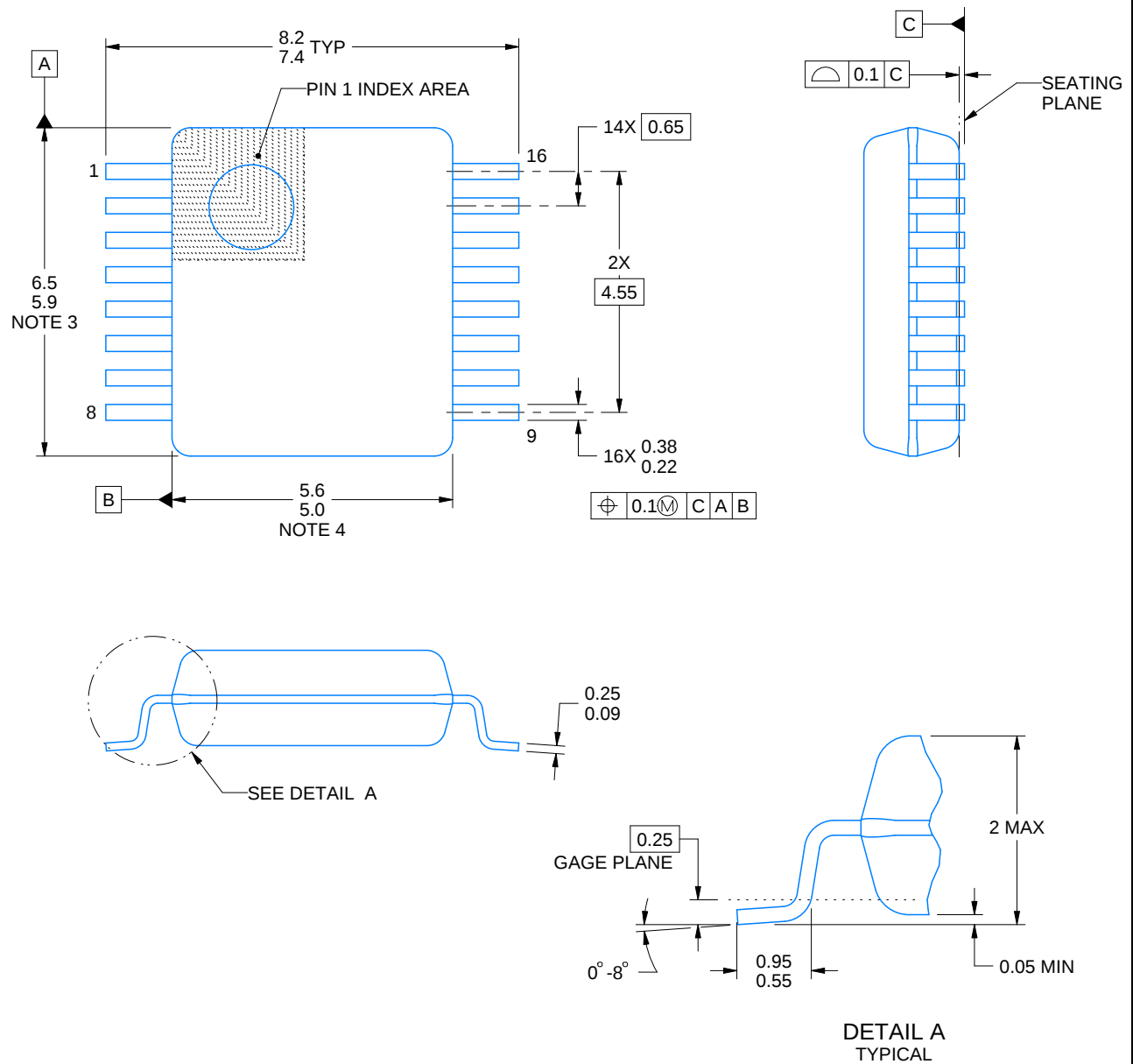
D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.



4220763/A 05/2022

NOTES:

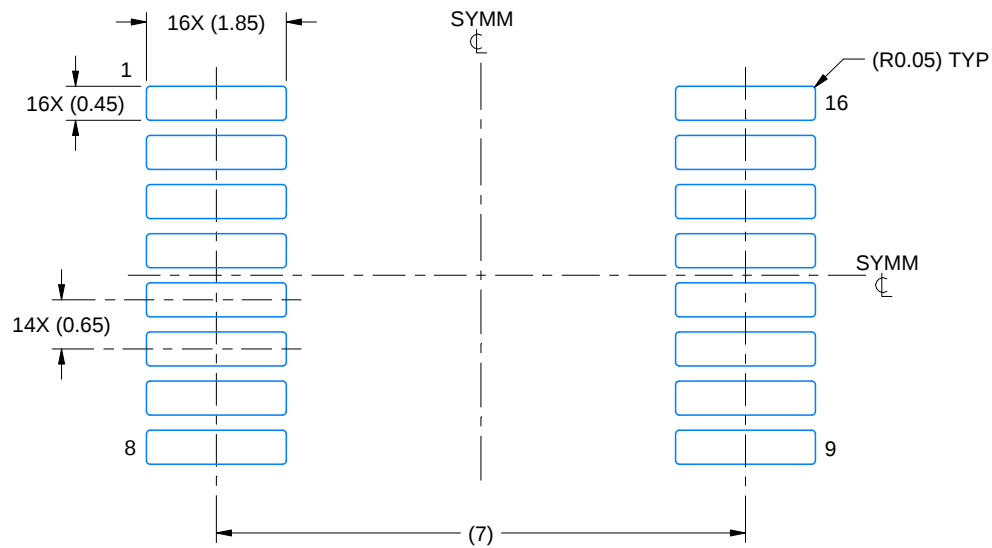
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

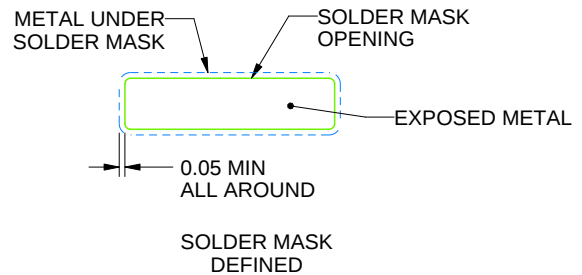
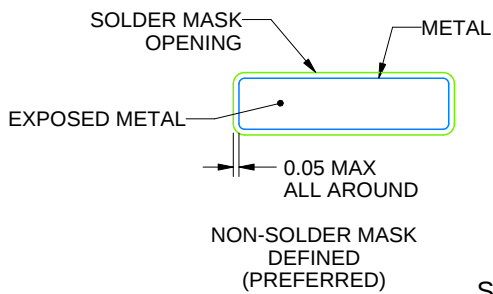
DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220763/A 05/2022

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

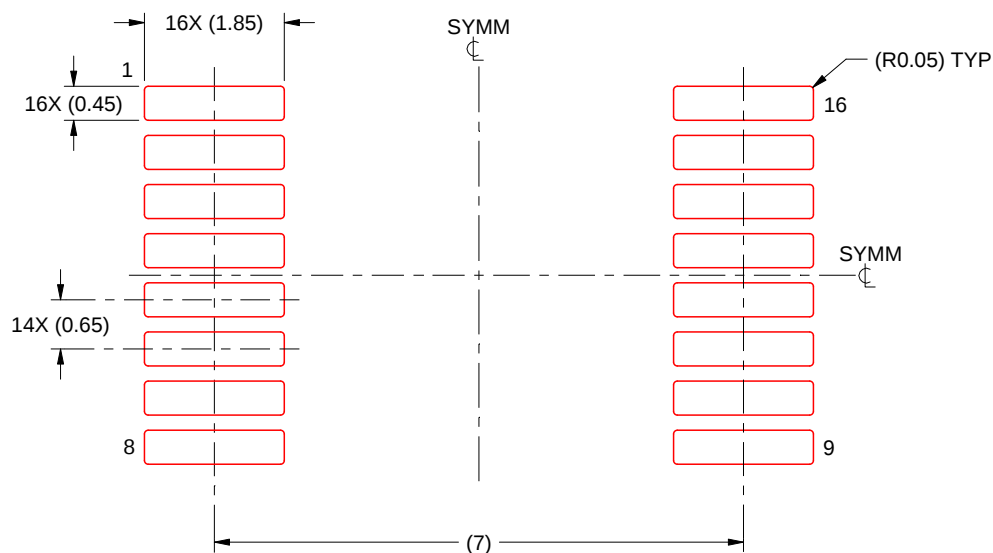
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

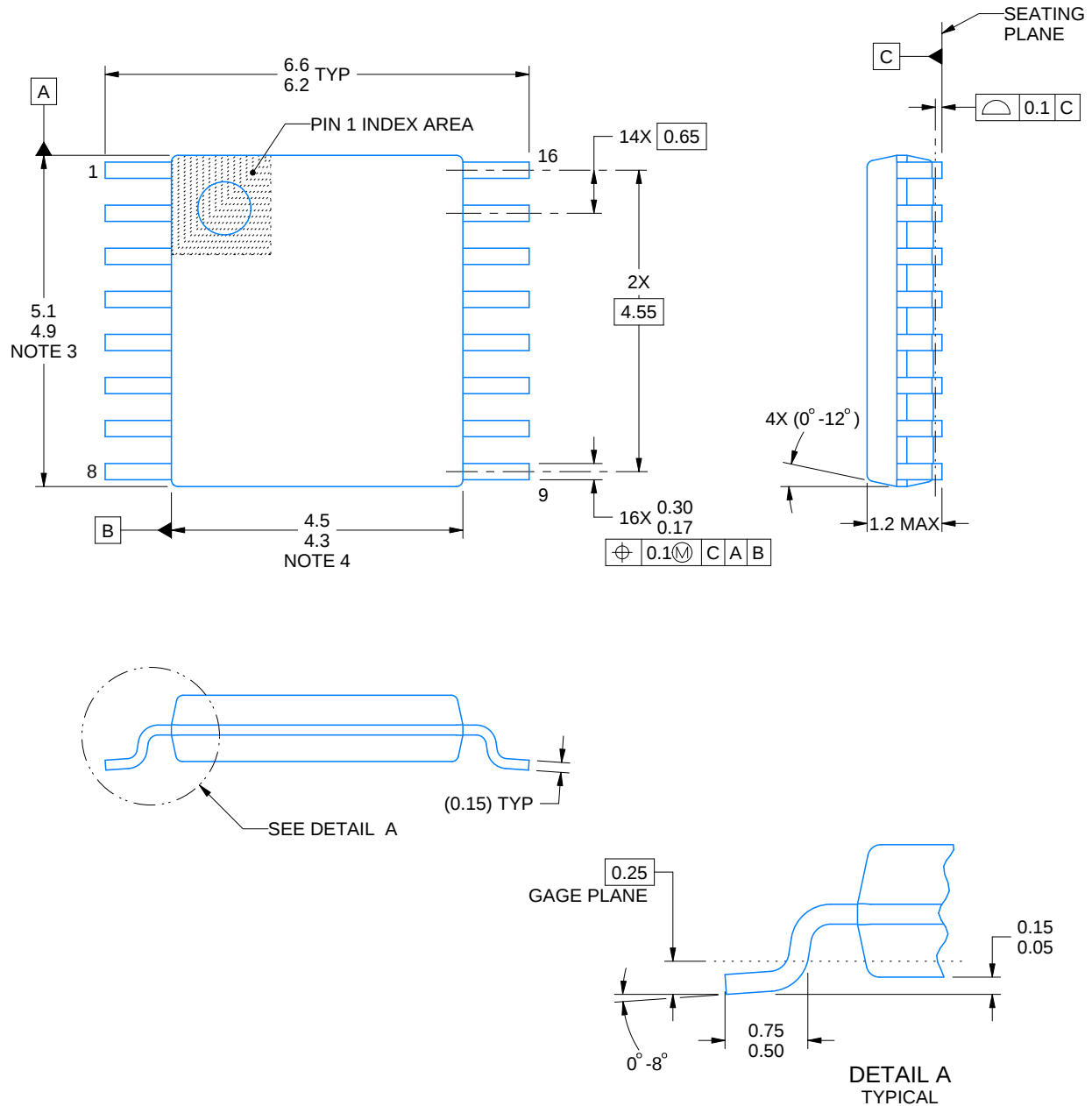
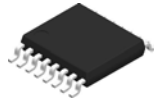


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.



4220204/B 12/2023

NOTES:

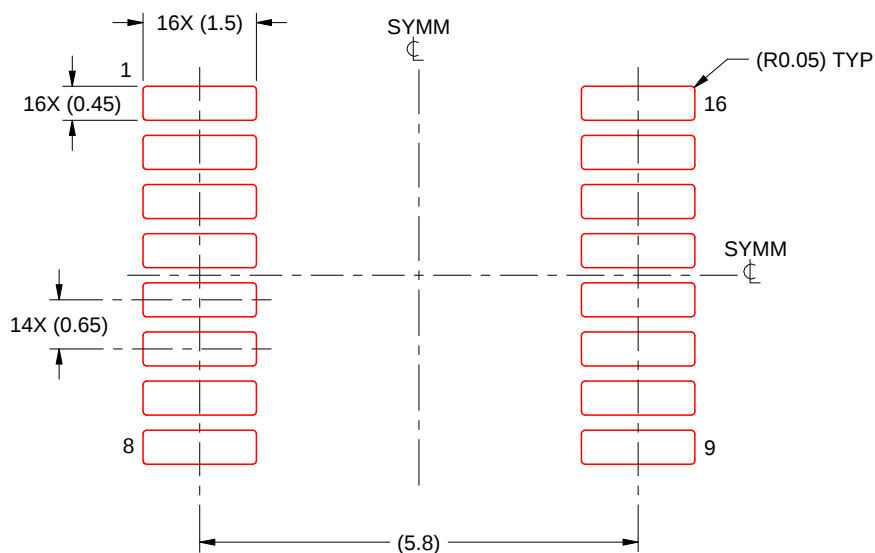
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

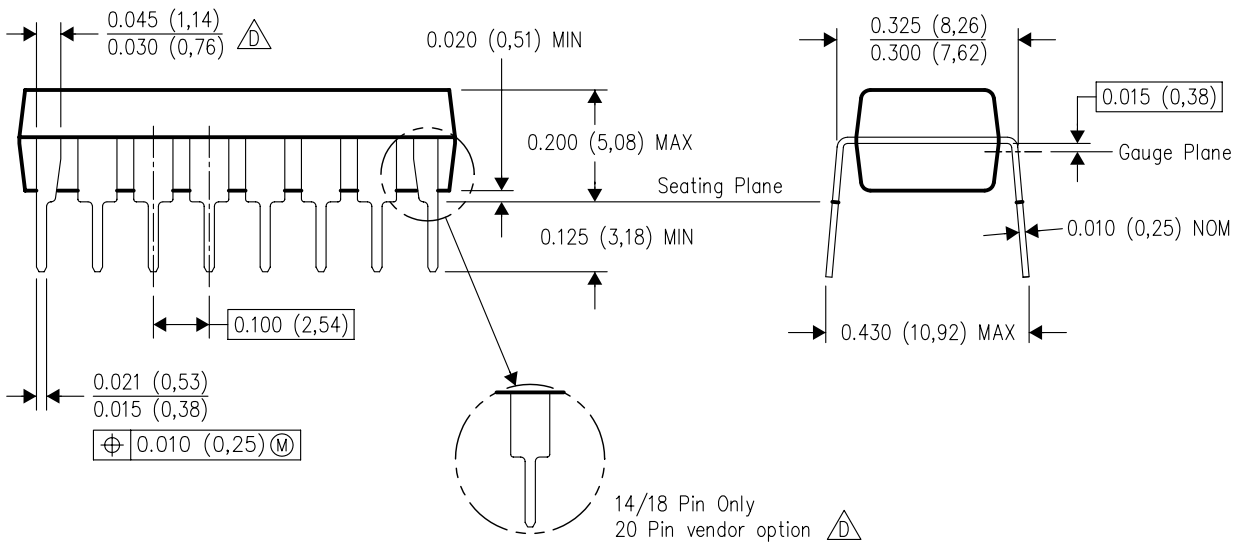
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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